



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akira SATO

Application No.: 09/424,500

Filed: February 22, 2000

For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, MOLDING  
DEVICE FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

Group Art Unit: 2825

Examiner: M. Smith

Docket No.: 104788

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SUPPLEMENTAL AMENDMENT

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

As a supplement to the Amendment filed on July 15, 2002, and further to the personal interview between Applicant's representative and Examiner Smith conducted on September 10, 2002, please further amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1, 12 and 15 as follows:

1. (Twice Amended) A method of manufacturing a semiconductor device comprising:

placing a semiconductor assembly in which a semiconductor chip is secured to a die pad of a lead frame in a cavity of a mold;

applying a pressure to the semiconductor assembly by at least one support pin so as to cause a stress in the lead frame;

sealing the semiconductor assembly with a resin injected into the cavity from a resin injection port of the mold, the pressure applied by the at least one support pin